$10.000 \pm 0.075$ 

PIN 1 ID

5.000 ± 0.075 -NOTE 9

- (1.818)

PAD A1

## ILCC48 10x10 CASE 847AC **ISSUE B**

В

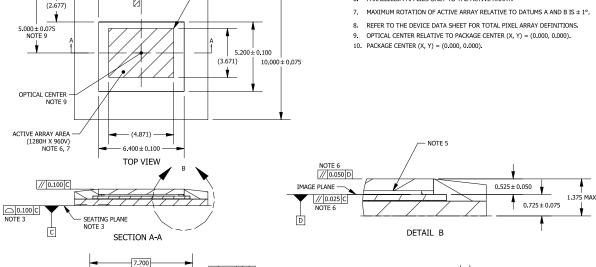
Α

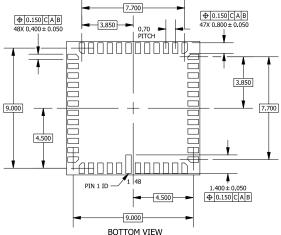
FIRST ACTIVE

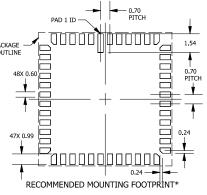
## **DATE 13 FEB 2020**

## NOTES

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS [mm].
- 3. COPLANARITY APPLIES TO THE PLATED LAND PADS
- GLASS: 0.400 THICKNESS; REFRACTIVE INDEX = 1.52. 4.
- AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.125 THICKNESS. 5.
- PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.

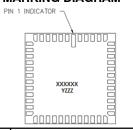






\*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD
THE ON SEMICONDUCTOR SOLDERING AND MOUNTING
TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

## **GENERIC MARKING DIAGRAM\***



XXXX = Specific Device Code

= Year

= Lot Traceability ZZZ

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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